

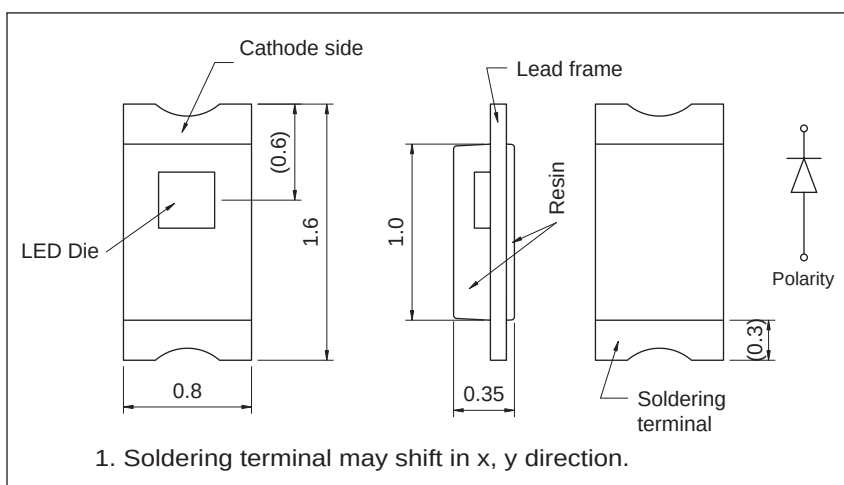
Characters

- Chip LED (1.6x0.8x0.35)
- Super compact type
- Lead frame type

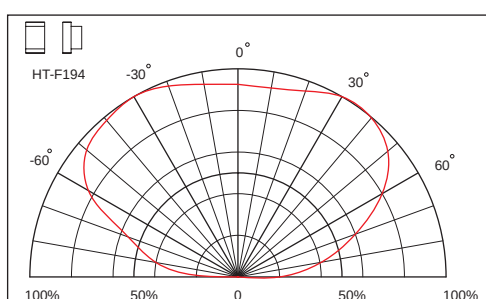
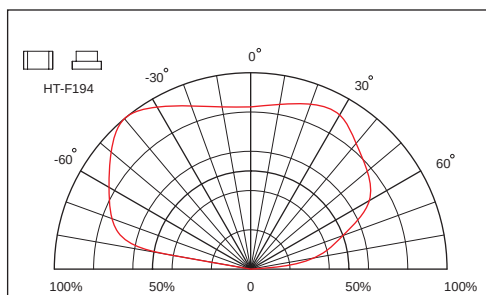


Package Outline Dimensions

(Unit:mm Tolerance:+/-0.1)

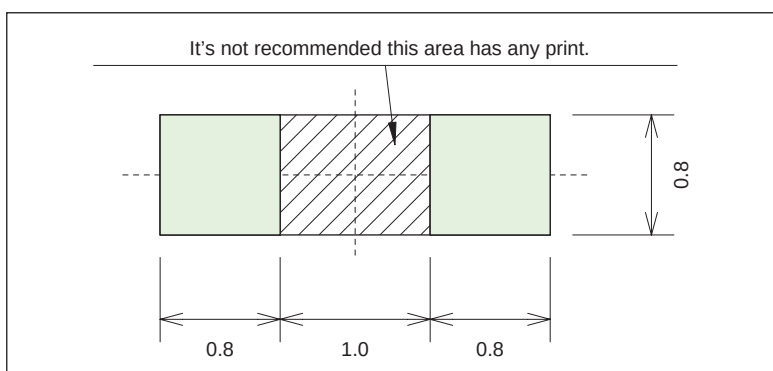


Directive Characteristics



Recommended Soldering Pattern

Unit: mm



Absolute Maximum Ratings

(Ta=25 °C)

Item	Symbol	Value	Unit
		InGaN	
Power Dissipation	P _D	117	mW
DC Forward Current	I _F	30	mA
Pulsed Forward Current	I _{FP} *	100	mA
Reverse Voltage (I _R =100uA)	V _R	5	V
Operating Temperature	T _{OP}	-30 to 80	°C
Storage Temperature	T _{ST}	-40 to 85	°C

*Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width

Electrical-Optical Characteristics

(Ta=25 °C)

Code for parts	Lighting Color	Material	I _F =20mA							I _F =5mA						
			Forward Voltage (V)		Wavelength (nm) typ			Luminous Intensity (mcd)*		Forward Voltage (V)		Wavelength (nm) typ			Luminous Intensity (mcd)*	
			typ	max	λ _D	λ _P	Δλ	min	typ	typ	max	λ _D	λ _P	Δλ	min	typ
HT-F194NB	Blue	InGaN	3.3	3.9	470	468	40	25	60	2.8	3.15	472	470	40	10	25
HT-F194NG	Green	InGaN	3.3	3.9	527	520	40	63	160	2.8	3.15	529	522	40	25	50
HT-F194NW	White	InGaN	3.3	3.9	X=0.29 Y=0.31	468	-	100	250	2.8	3.15	X=0.29 Y=0.32	470	-	40	80

*Per NIST standards